

Description

The HSM6040 is the high cell density trenched N-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

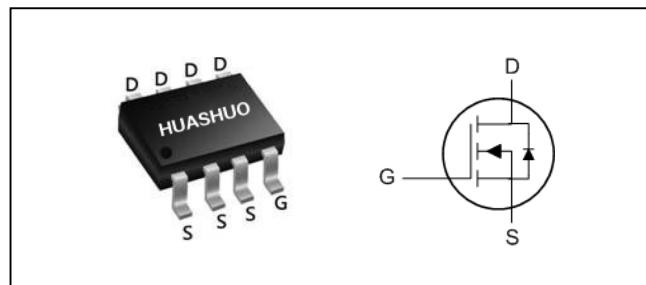
The HSM6040 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

- Super Low Gate Charge
- 100% EAS Guaranteed
- Green Device Available
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology

Product Summary

V _{DS}	60	V
R _{DS(ON),max}	5.2	mΩ
I _D	18	A

SOP8 Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	60	V
V _{GS}	Gate-Source Voltage	±20	V
I _D @T _A =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	18	A
I _D @T _A =100°C	Continuous Drain Current, V _{GS} @ 10V ¹	14	A
I _{DM}	Pulsed Drain Current ²	130	A
EAS	Single Pulse Avalanche Energy ³	125	mJ
I _{AS}	Avalanche Current	50	A
P _D @T _A =25°C	Total Power Dissipation ⁴	3.1	W
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-ambient ¹ (t≤10S)	---	45	°C/W
	Thermal Resistance Junction-ambient ¹ (Steady State)	---	80	°C/W



Electrical Characteristics ($T_J=25^{\circ}\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=250\mu\text{A}$	60	---	---	V
$\text{R}_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance ²	$\text{V}_{\text{GS}}=10\text{V}, \text{I}_D=18\text{A}$	---	4.3	5.2	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=4.5\text{V}, \text{I}_D=16\text{A}$	---	6	7	$\text{m}\Omega$
$\text{V}_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$\text{V}_{\text{GS}}=\text{V}_{\text{DS}}, \text{I}_D=250\mu\text{A}$	1.2	---	2.5	V
I_{DSS}	Drain-Source Leakage Current	$\text{V}_{\text{DS}}=48\text{V}, \text{V}_{\text{GS}}=0\text{V}, \text{T}_J=25^{\circ}\text{C}$	---	---	1	uA
		$\text{V}_{\text{DS}}=48\text{V}, \text{V}_{\text{GS}}=0\text{V}, \text{T}_J=55^{\circ}\text{C}$	---	---	5	
I_{GSS}	Gate-Source Leakage Current	$\text{V}_{\text{GS}}=\pm 20\text{V}, \text{V}_{\text{DS}}=0\text{V}$	---	---	± 100	nA
g_{fs}	Forward Transconductance	$\text{V}_{\text{DS}}=5\text{V}, \text{I}_D=18\text{A}$	---	65	---	S
Q_{g}	Total Gate Charge (10V)	$\text{V}_{\text{DS}}=48\text{V}, \text{V}_{\text{GS}}=10\text{V}, \text{I}_D=18\text{A}$	---	75	---	nC
Q_{gs}	Gate-Source Charge		---	15.5	---	
Q_{gd}	Gate-Drain Charge		---	20.3	---	
$\text{T}_{\text{d}(\text{on})}$	Turn-On Delay Time	$\text{V}_{\text{DD}}=30\text{V}, \text{V}_{\text{GS}}=10\text{V}, \text{R}_G=3.3\Omega,$ $\text{I}_D=18\text{A}$	---	18.5	---	ns
T_r	Rise Time		---	8.8	---	
$\text{T}_{\text{d}(\text{off})}$	Turn-Off Delay Time		---	58.8	---	
T_f	Fall Time		---	15.8	---	
C_{iss}	Input Capacitance	$\text{V}_{\text{DS}}=25\text{V}, \text{V}_{\text{GS}}=0\text{V}, \text{f}=1\text{MHz}$	---	4706	---	pF
C_{oss}	Output Capacitance		---	325	---	
C_{rss}	Reverse Transfer Capacitance		---	245	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current ^{1,5}	$\text{V}_G=\text{V}_D=0\text{V}$, Force Current	---	---	18	A
I_{SM}	Pulsed Source Current ^{2,5}		---	---	130	A
V_{SD}	Diode Forward Voltage ²	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_s=1\text{A}, \text{T}_J=25^{\circ}\text{C}$	---	---	1.2	V
t_{rr}	Reverse Recovery Time	$\text{I}_F=18\text{A}, \text{dI}/\text{dt}=100\text{A}/\mu\text{s},$	---	22.9	---	nS
Q_{rr}	Reverse Recovery Charge	$\text{T}_J=25^{\circ}\text{C}$	---	11.6	---	nC

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is $\text{V}_{\text{DD}}=50\text{V}, \text{V}_{\text{GS}}=10\text{V}, \text{L}=0.1\text{mH}, \text{I}_{\text{AS}}=50\text{A}$
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.



Typical Characteristics

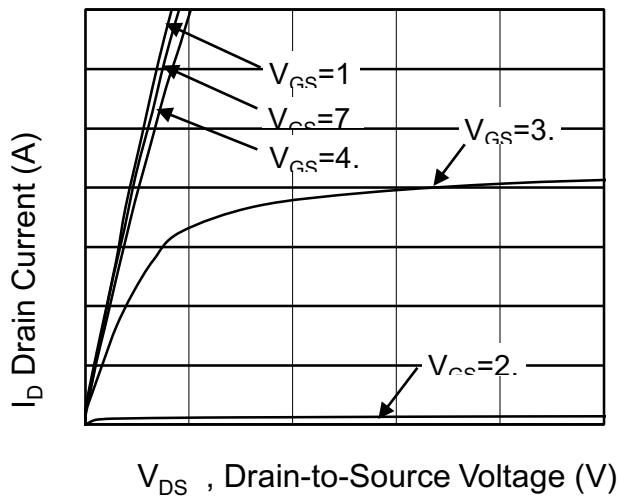


Fig.1 Typical Output Characteristics

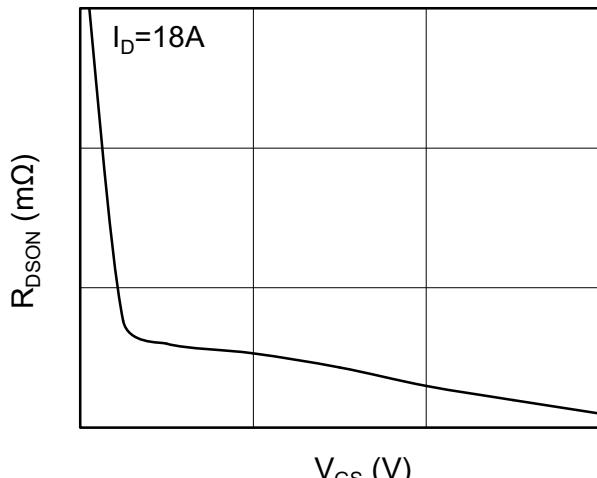


Fig.2 On-Resistance v.s Gate-Source

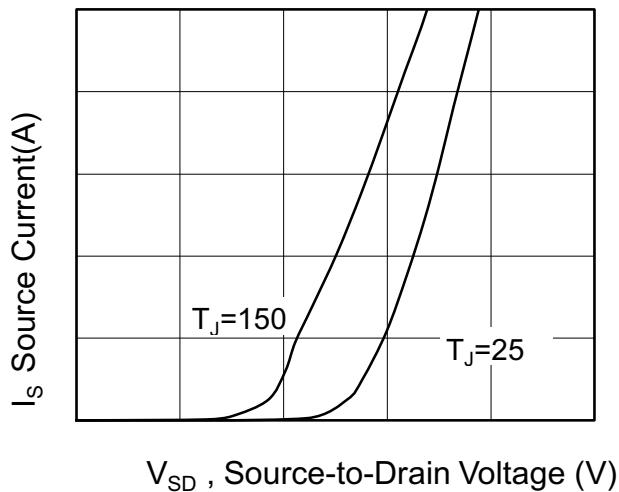


Fig.3 Forward Characteristics of Reverse

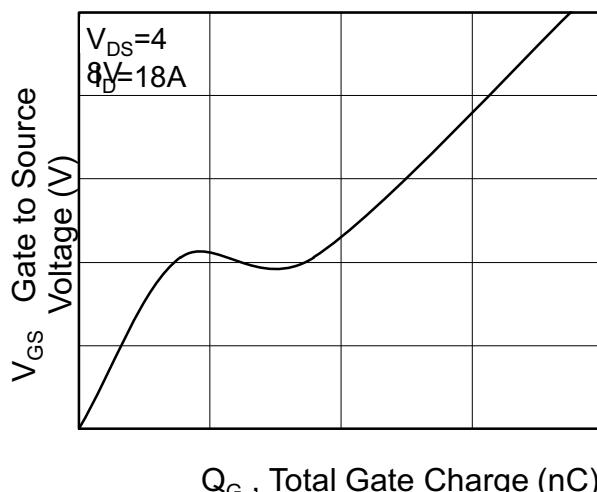


Fig.4 Gate-Charge Characteristics

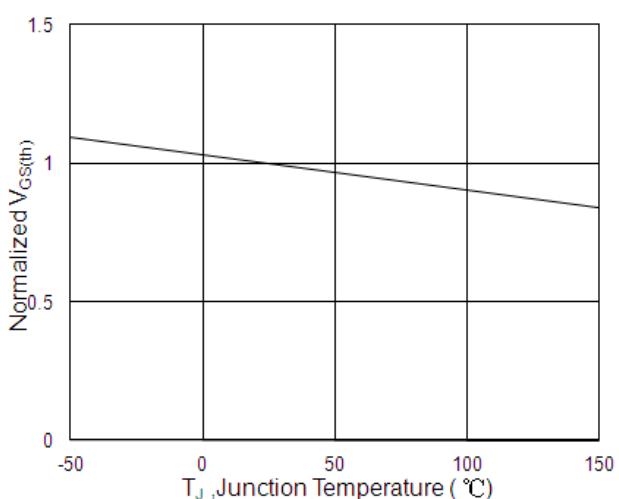


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

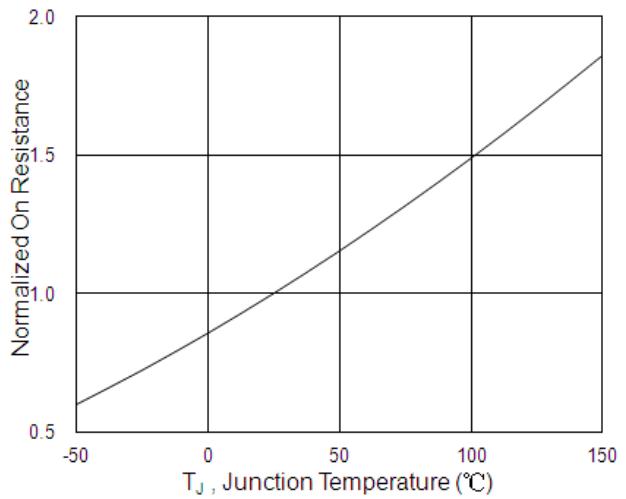
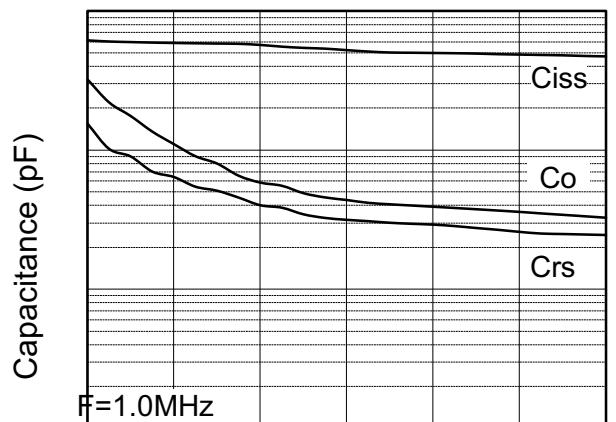
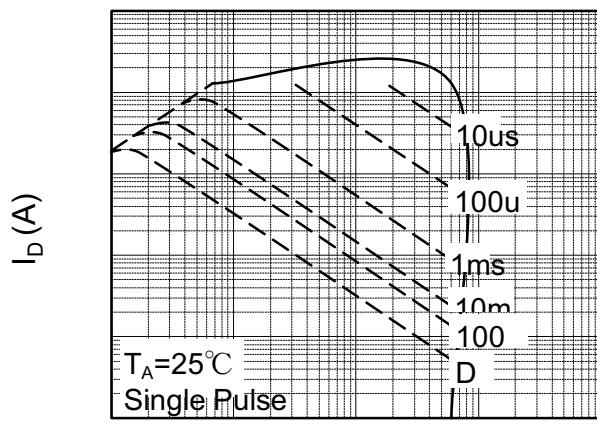


Fig.6 Normalized R_{DSON} vs. T_J



V_{DS} , Drain to Source Voltage(V)



V_{DS} (V)

Fig.7 Capacitance

Fig.8 Safe Operating Area

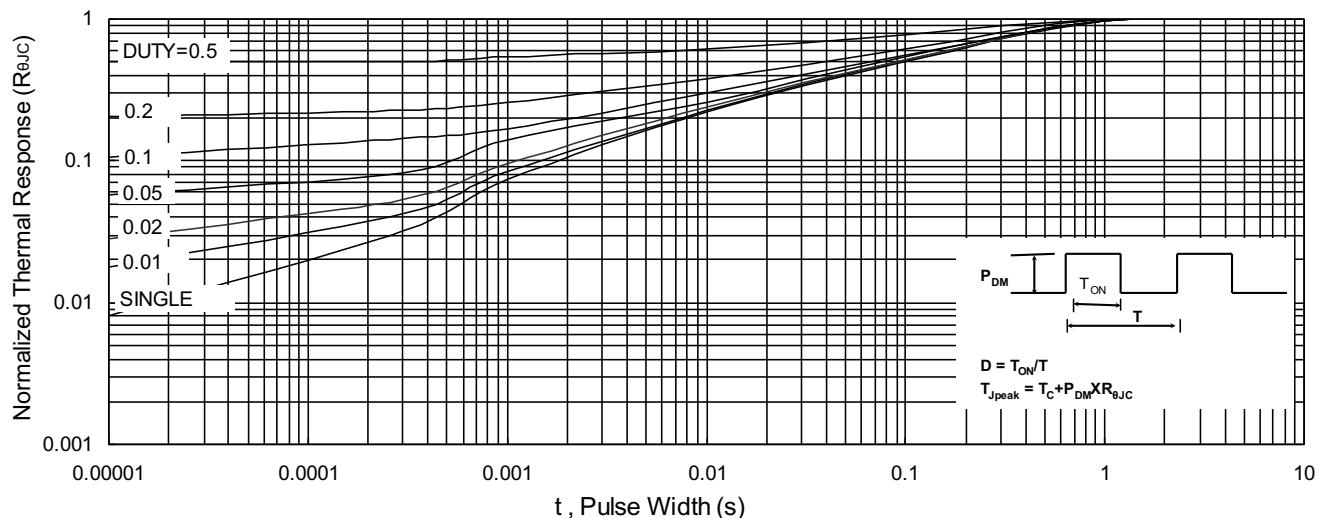


Fig.9 Normalized Maximum Transient Thermal Impedance

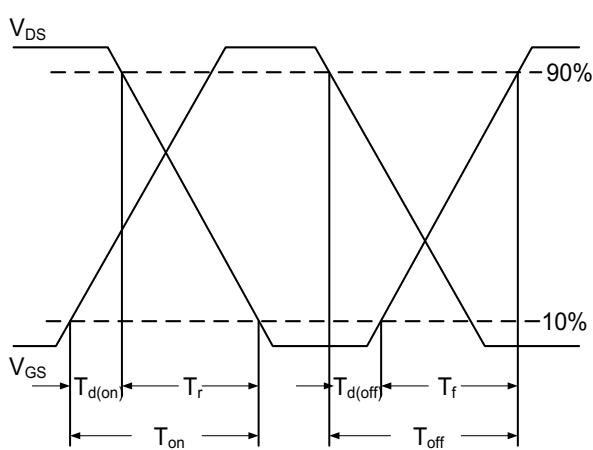


Fig.10 Switching Time Waveform

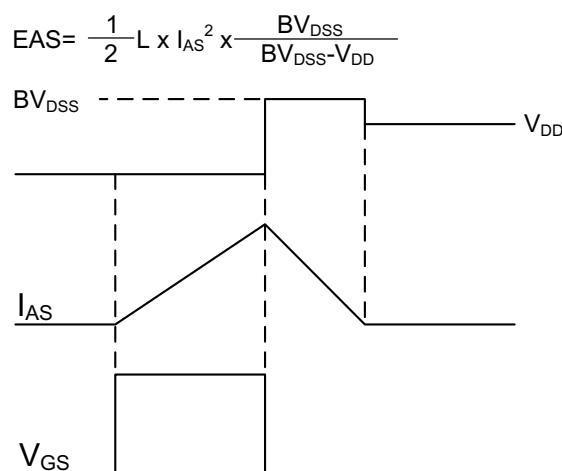


Fig.11 Unclamped Inductive Switching



Ordering Information

Part Number	Package code	Packaging
HSM6040	SOP-8	2500/Tape&Reel

